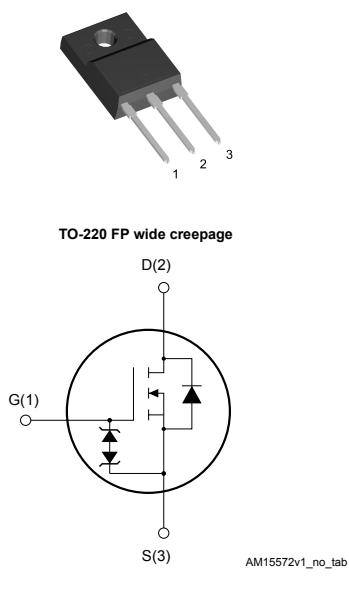


## N-channel 600 V, 0.255 $\Omega$ typ., 13 A MDmesh M2 Power MOSFET in a TO-220FP wide creepage package



### Features

Order code	$V_{DS} @ T_{Jmax}$	$R_{DS(on)} \text{ max.}$	$I_D$
STFH18N60M2	650 V	0.280 $\Omega$	13 A

- Extremely low gate charge
- Excellent output capacitance ( $C_{oss}$ ) profile
- 100% avalanche tested
- Zener-protected
- Wide distance of 4.25 mm between the pins

### Applications

- Switching applications
- LCC converters
- Resonant converters

### Description

This device is an N-channel Power MOSFET developed using MDmesh M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

The TO-220FP wide creepage package provides increased surface insulation for Power MOSFETs to prevent failure due to arcing, which can occur in polluted environments.



#### Product status link

[STFH18N60M2](#)

#### Product summary

Order code	STFH18N60M2
Marking	18N60M2
Package	TO-220FP wide creepage
Packing	Tube

## 1 Electrical ratings

**Table 1.** Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$ <sup>(1)</sup>	Drain current (continuous) at $T_C = 25^\circ\text{C}$	13	A
	Drain current (continuous) at $T_C = 100^\circ\text{C}$	8	A
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	52	A
$P_{TOT}$	Total power dissipation at $T_C = 25^\circ\text{C}$	25	W
$dv/dt$ <sup>(3)</sup>	Peak diode recovery voltage slope	15	V/ns
$dv/dt$ <sup>(4)</sup>	MOSFET dv/dt ruggedness	50	V/ns
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t = 1 \text{ s}$ ; $T_C = 25^\circ\text{C}$ )	2.5	kV
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 13 \text{ A}$ ,  $di/dt \leq 400 \text{ A}/\mu\text{s}$ ;  $V_{DS(peak)} < V_{(BR)DSS}$ ,  $V_{DD} = 400 \text{ V}$
4.  $V_{DS} \leq 480 \text{ V}$

**Table 2.** Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	5	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	$^\circ\text{C/W}$

**Table 3.** Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )	3	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j=25^\circ\text{C}$ , $I_D=I_{AR}$ , $V_{DD}=50 \text{ V}$ )	135	mJ

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified).

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	600			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}$ (1)			100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$		0.255	0.280	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	791	-	pF
$C_{oss}$	Output capacitance		-	40	-	pF
$C_{rss}$	Reverse transfer capacitance		-	1.3	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	164.5	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	5.6	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 13 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	21.5	-	nC
$Q_{gs}$	Gate-source charge		-	3.2	-	nC
$Q_{gd}$	Gate-drain charge		-	11.3	-	nC

1.  $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 6.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	12	-	ns
$t_r$	Rise time		-	9	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	47	-	ns
$t_f$	Fall time		-	10.6	-	ns

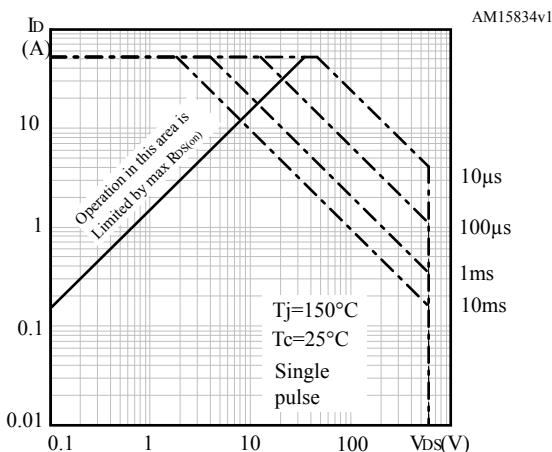
**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		13	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		52	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 13 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 13 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	305		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	3.3		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	22		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 13 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	417		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	4.6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	22		A

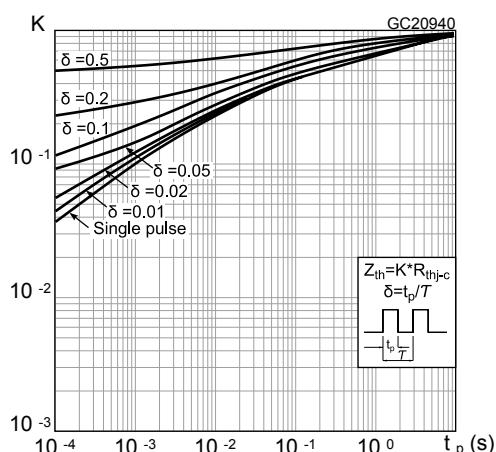
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

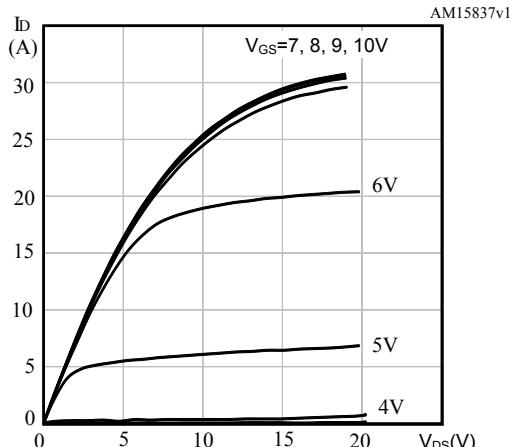
**Figure 1. Safe operating area**



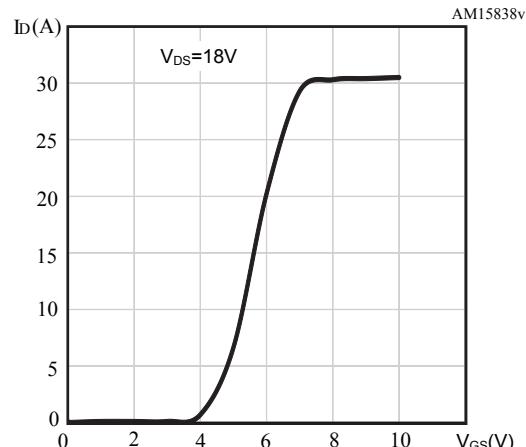
**Figure 2. Thermal impedance**



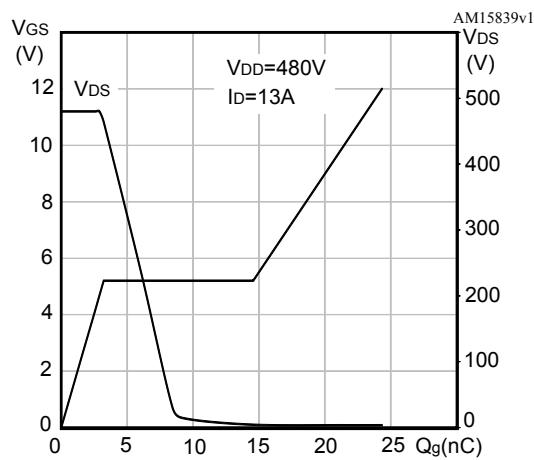
**Figure 3. Output characteristics**



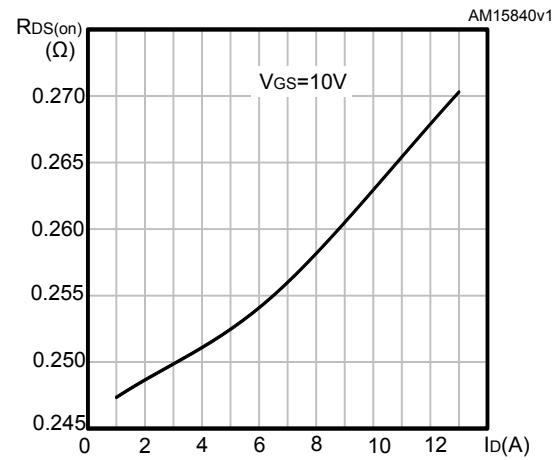
**Figure 4. Transfer characteristics**

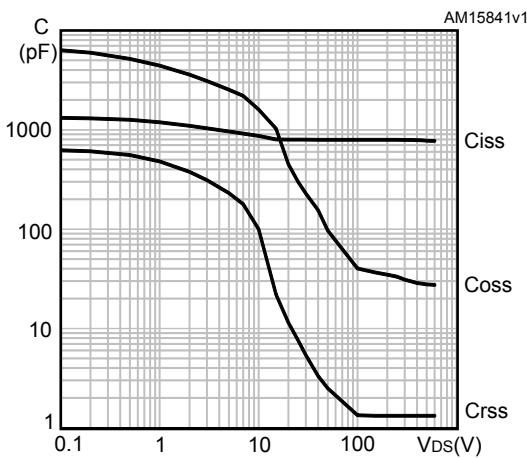
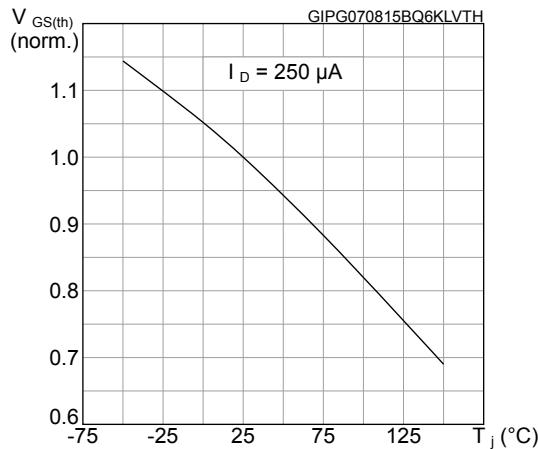
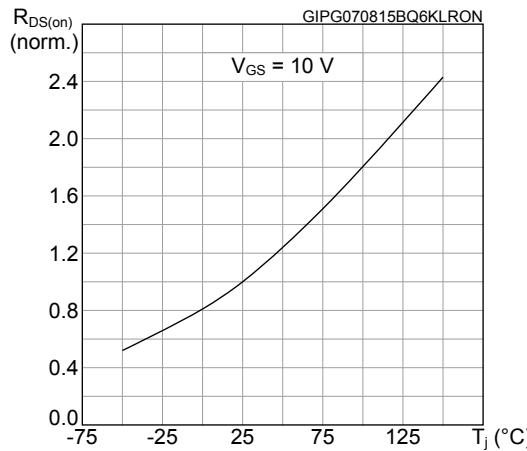
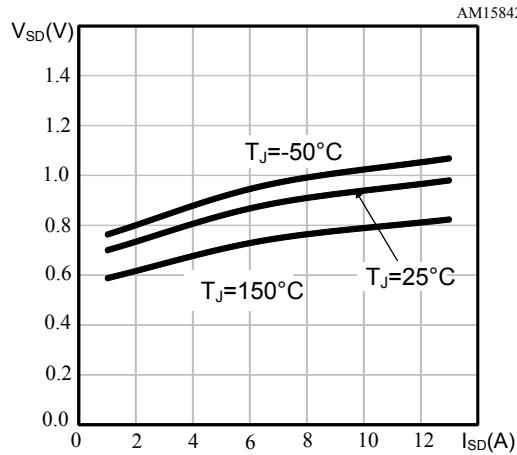
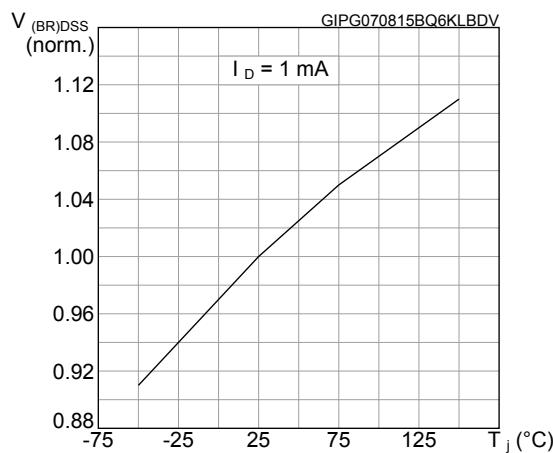
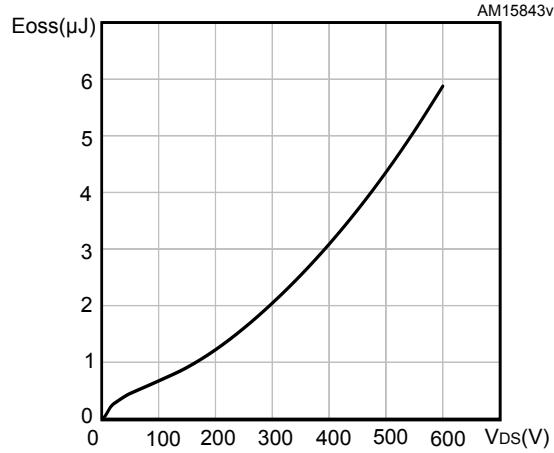


**Figure 5. Gate charge vs gate-source voltage**



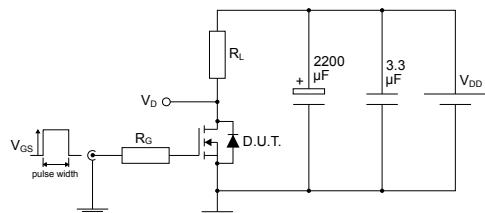
**Figure 6. Static drain-source on-resistance**



**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs. temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Source-drain diode forward characteristics**

**Figure 11. Normalized V<sub>(BR)DSS</sub> vs temperature**

**Figure 12. Output capacitance stored energy**


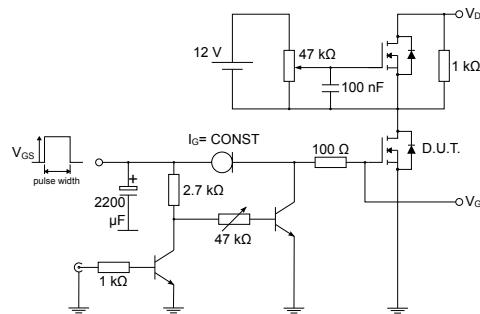
### 3 Test circuits

**Figure 13.** Test circuit for resistive load switching times



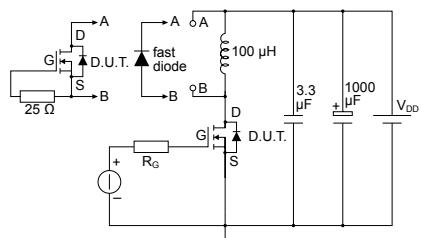
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**Figure 14.** Test circuit for gate charge behavior



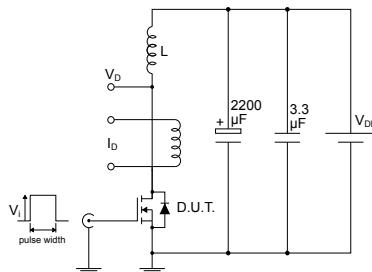
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**Figure 15.** Test circuit for inductive load switching and diode recovery times



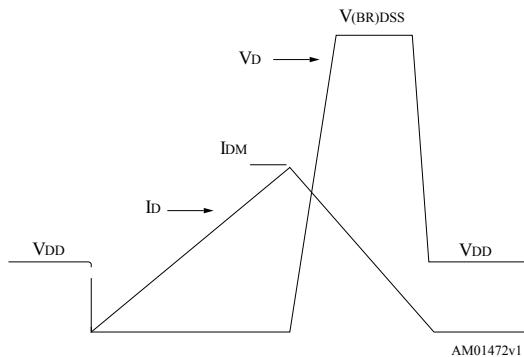
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**Figure 16.** Unclamped inductive load test circuit



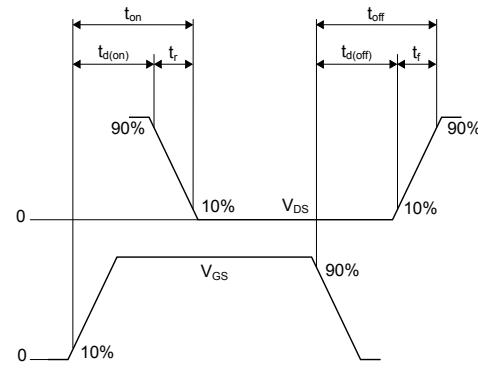
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**Figure 17.** Unclamped inductive waveform



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**Figure 18.** Switching time waveform



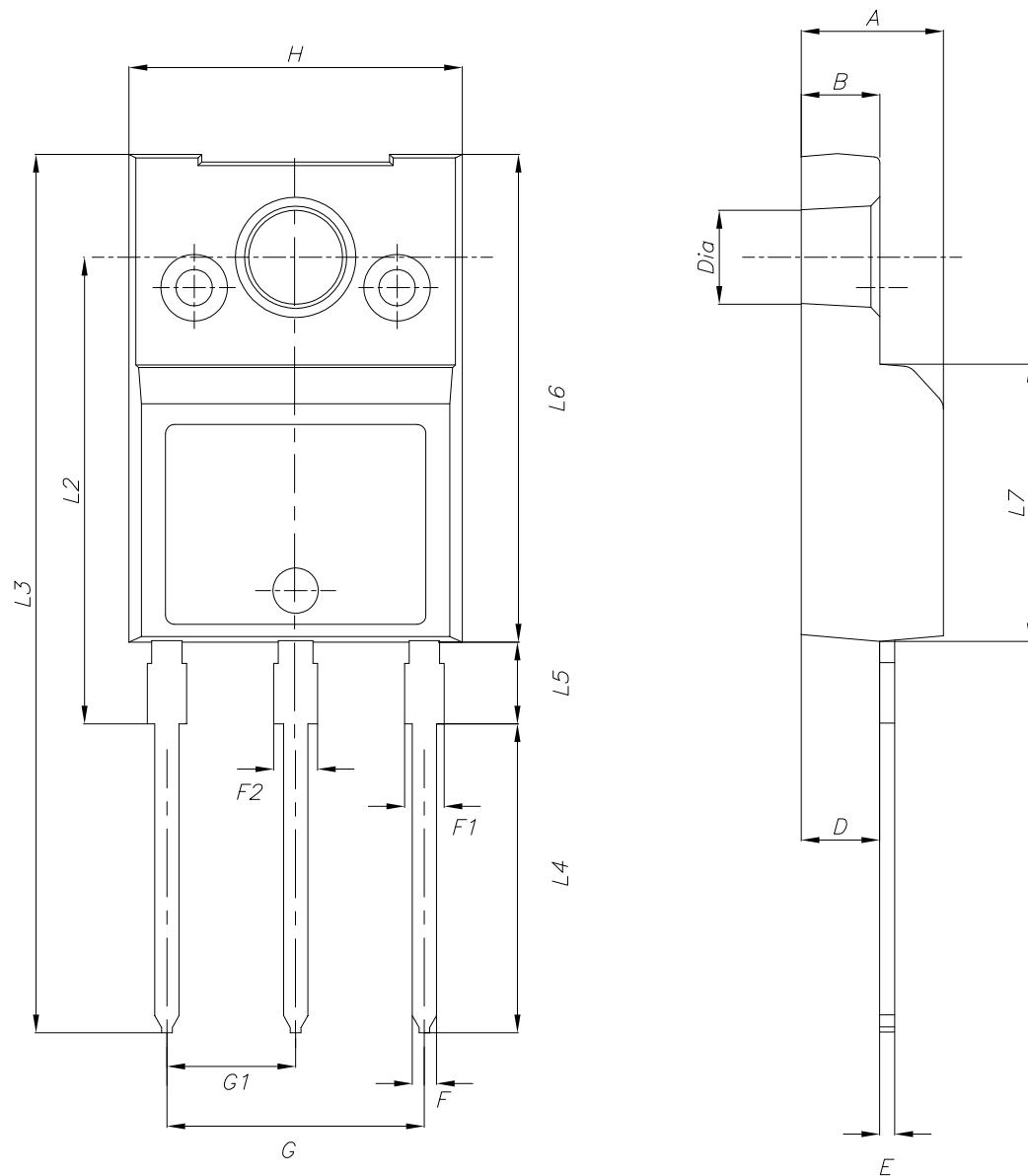
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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-220FP wide creepage package information

Figure 19. TO-220FP wide creepage package outline



DM00260252\_1

**Table 8.** TO-220FP wide creepage package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.70	4.80
B	2.50	2.60	2.70
D	2.49	2.59	2.69
E	0.46		0.59
F	0.76		0.89
F1	0.96		1.25
F2	1.11		1.40
G	8.40	8.50	8.60
G1	4.15	4.25	4.35
H	10.90	11.00	11.10
L2	15.25	15.40	15.55
L3	28.70	29.00	29.30
L4	10.00	10.20	10.40
L5	2.55	2.70	2.85
L6	16.00	16.10	16.20
L7	9.05	9.15	9.25
Dia	3.00	3.10	3.20

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
08-Jun-2016	1	First release.
16-Jun-2016	2	Document status promoted from preliminary data to production data. Minor text changes.
06-Jun-2019	3	Modified <a href="#">Figure 8. Normalized gate threshold voltage vs. temperature</a> , <a href="#">Figure 9. Normalized on-resistance vs temperature</a> and <a href="#">Figure 11. Normalized V<sub>(BR)DSS</sub> vs temperature</a> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings .....</b>	<b>2</b>
<b>2</b>	<b>Electrical characteristics.....</b>	<b>3</b>
<b>2.1</b>	Electrical characteristics (curves) .....	5
<b>3</b>	<b>Test circuits .....</b>	<b>7</b>
<b>4</b>	<b>Package information.....</b>	<b>8</b>
<b>4.1</b>	TO-220FP wide creepage package information .....	8
	<b>Revision history .....</b>	<b>10</b>

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